



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPB033N10N5LF	<b>Issued</b>	10. June 2021
<b>MA#</b>	MA001616166		
<b>Package</b>	PG-TO263-3-2	<b>Weight*</b>	1562.69 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	3.991	0.26	0.26	2554	2554
chip_2	inorganic material	silicon	7440-21-3	0.390	0.02	0.02	250	250
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.46	19.49	194553	194806
wire	noble metal	gold	7440-57-5	0.078			50	
	non noble metal	aluminium	7429-90-5	13.525	0.87	0.87	8655	8705
encapsulation	inorganic material	zinc oxide	1314-13-2	6.782	0.43		4340	
	miscellaneous	miscellaneous	-	27.130	1.74		17361	
	plastics	epoxy resin	-	101.737	6.51		65104	
	inorganic material	silicon dioxide	60676-86-0	542.597	34.72	43.40	347220	434025
lead finish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6180	6180
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.073			47	
	noble metal	silver	7440-22-4	0.091	0.01		58	
	non noble metal	lead	7439-92-1	3.487	0.22	0.23	2231	2336
glue	plastics	Polyimide	26023-21-2	0.124	0.01	0.01	79	79
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		351	
	non noble metal	copper	7440-50-8	547.666	35.04	35.09	350462	350918
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

- Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
- Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
- All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com